

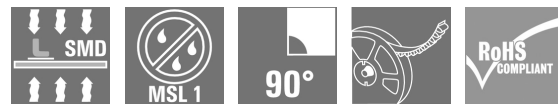
RJ45M S1D DE4N RL**Weidmüller Interface GmbH & Co. KG**

Klingenbergstraße 26

D-32758 Detmold

Germany

www.weidmueller.com



RJ45 transmitter sockets (magnetics) for gigabit applications (1000 base-T) with integrated compensation actively counteracts inductive and capacitive couplings and saves space on the PCB.

The product range encompasses the following designs:

- 90°, lying (horizontal) and 180°, standing (vertical)
- latch up / latch down
- THT, THR or SMD soldering processes
- Wide range of different design types, also with integrated LEDs and shield contact tabs
- Transmission rates of up to 1 Gbps
- Packed either in a tray (TY) or on a roll (tape-on-reel, RL)
- Compatible with modular RJ45 connector according to ANSI / TIA-1096-A and IEC 60603
- Dielectric strength ≥ 1500 V AC RMS (2250 V AC peak value) according to IEEE 802.3
- Dielectric strength ≥ 1500 V AC (peak value) or ≥ 1500 V DC according to IEC 60603
- Compliance with IEEE 802.3 requirements (1000Base-T, 1 Gbps, IEEE 802.3ab or 100Base-Tx, 100 Mbps, IEEE 802.3u)

Properties and advantages:

- Extended temperature range of -40 °C to $+85$ °C for maximum performance
- Reinforced gold layer (30µ") for improved corrosion protection

- At least 0.3mm stand-off ensures a perfect soldering result

General ordering data

Version	PCB plug-in connector, RJ45 jacks transformer, 10/100 MBit/s , SMD solder connection, 90°, Latch option: bottom, Shield tabs: 6 tabs, 30...80 µ" Ni / ≥ 30 µ" Au , LED: No, Number of poles: 8, Tape
Order No.	2564450000
Type	RJ45M S1D DE4N RL
GTIN (EAN)	4050118572940
Qty.	220 pc(s).
Packaging	Tape

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Technical data

Dimensions and weights

Depth	21.55 mm	Depth (inches)	0.848 inch
Height	13.46 mm	Height (inches)	0.53 inch
Height of lowest version	12.86 mm	Width	16 mm
Width (inches)	0.63 inch	Net weight	0.001 g

System specifications

Coplanarity:	100 µm	LED	No
Latch option	bottom	Mounting onto the PCB	SMD solder connection
Number of poles	8	Number of solder pins per pole	1
Outgoing elbow	90°	Performance-Category	10/100 MBit/s
Pitch in inches (P)	0.05 "	Pitch in mm (P)	1.27 mm
Plugging cycles	750	Product family	OMNIMATE Data - RJ45 transformer jack
Protection degree	IP20	Shield surface	nickel-plated
Shield tabs	6 tabs	Shielding	Yes
Shielding material	Brass	Solder pin dimensions	Octagonal
Solder pin length (l)	0 mm	Soldering process	Reflow soldering, Manual soldering
Tolerance of solder pin position	± 0.1 mm	Transmission rate	10/100 MBit/s
Type of connection	SMT solder connection		

Electrical properties

Dielectric strength, contact / contact	1000 V DC	Dielectric strength, contact / shield	1500 V DC
Rated current	1.5 A	Rated voltage	125 V

Material data

Insulating material	PA 9T	Colour	black
Colour chart (similar)	RAL 9011	Insulating material group	II
Comparative Tracking Index (CTI)	≥ 500	Moisture Level (MSL)	1
UL 94 flammability rating	V-0	Contact base material	Phosphorus bronze
Contact material	Cu-alloy	Contact surface	Gold over nickel
Layer structure of plug contact	30...80 µ" Ni / ≥ 30 µ" Au	Storage temperature, min.	-40 °C
Storage temperature, max.	85 °C	Operating temperature, min.	-40 °C
Operating temperature, max.	85 °C		

Packing

Packaging	Tape	VPE length	356 mm
VPE width	351 mm	VPE height	129 mm
Tape reel diameter Ø (A)	330 mm	Surface resistance	Rs = 10 ⁹ - 10 ¹² Ω

Classifications

ETIM 6.0	EC002637	ETIM 7.0	EC002637
ETIM 8.0	EC002637	ETIM 9.0	EC002637
ETIM 10.0	EC002637	ECLASS 9.1	27-44-04-02
ECLASS 10.0	27-44-04-02	ECLASS 11.0	27-46-02-01
ECLASS 12.0	27-46-02-01	ECLASS 13.0	27-46-02-01
ECLASS 14.0	27-46-02-01	ECLASS 15.0	27-46-02-01

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Technical data

Environmental Product Compliance

RoHS Compliance Status	Compliant without exemption
REACH SVHC	No SVHC above 0.1 wt%

Approvals

ROHS	Conform
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Downloads

Approval/Certificate/Document of Conformity	Certificate of Compliance
Catalogues	Catalogues in PDF-format

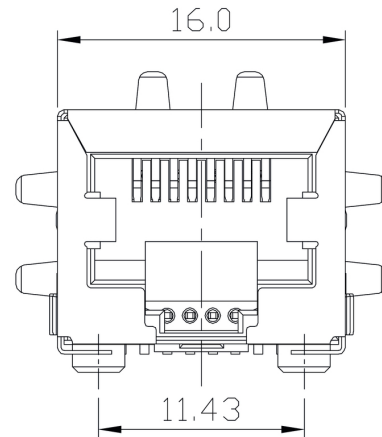
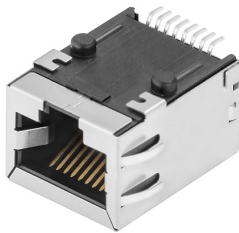
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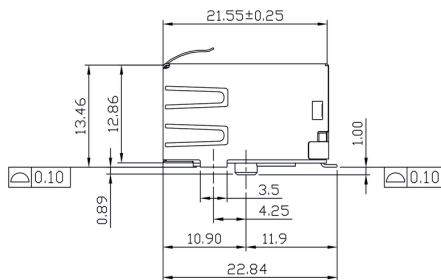
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Drawings

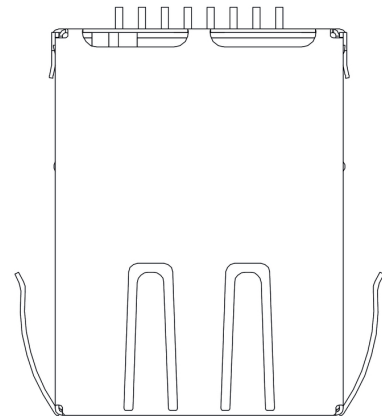
Dimensioned drawing



Dimensioned drawing



Dimensioned drawing

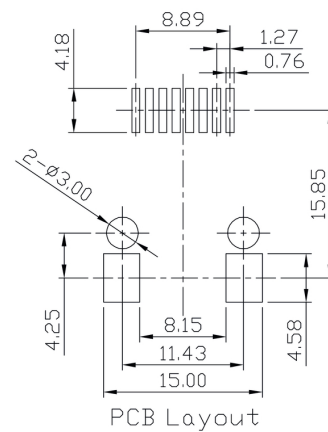


Dimensioned drawing

Characteristics

Inductance	350 µH min. @ 100 kHz, 100 mV, 8 mA DC Bias
Leakage Inductance	0.3 µH max. @ 100 kHz, 100 mV
Insertion Loss	1.1 dB max. @ (1 - 100) MHz
Return Loss	18 dB min. @ (1 - 30) MHz 16 dB min. @ (30 - 60) MHz 12 dB min. @ (60 - 80) MHz
Cross Talk	30 dB min. @ (1 - 100) MHz
Common Mode Rejection	30 dB min. @ (1 - 100) MHz

PCB design

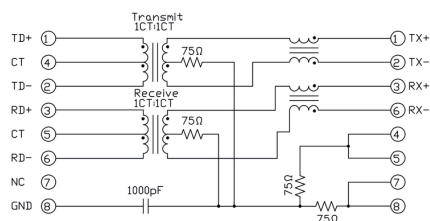


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www.weidmueller.com**Drawings****Wiring diagram**

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www.weidmueller.com**Drawings**

RJ45	G1	R	1	U	3.2	E	4	GY/GY	TY	RJ45G1 R1U 3.2E4GY/GY TY

Recommended reflow soldering profile

Weidmüller Interface GmbH & Co. KG
Klingenbergstraße 16
D-32758 Detmold
Germany
Fon: +49 5231 14-0
Fax: +49 5231 14-292083
www.weidmueller.com



Reflow soldering profile

The perfect soldering profile for SMT Surface Mount Technology is one the most exiting question in SMT production. But there are more than one correct answer: The diagram of temperature-on-time is related to processing features of solder paste and to maximum load of components.

We have to consider the following parameters:

- Time for pre heating
- Maximum temperature
- Time above melting point
- Time for cooling
- Maximum heating rate
- Maximum cooling rate

We recommend a typical solder profile with associated process limits. With preheating components and board are prepared smoothly for the solder phase. Heating rate is typically $\leq +3\text{K/s}$. In parallel the solder paste is 'activated'. The time above melting point of 217°C the paste gets liquid and components and boards begin to connect. The maximum temperature of 245°C to 254°C should stay between 10 and 40 seconds. In the cooling phase at $\geq -6\text{K/s}$ solder is cured. Board and components cool down while avoiding cold cracks.